2SC5407

Silicon NPN triple diffusion mesa type

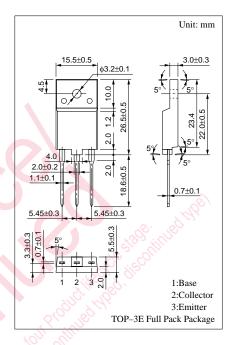
For horizontal deflection output

Features

- High breakdown voltage, and high reliability through the use of a glass passivation layer
- High-speed switching
- Wide area of safe operation (ASO)

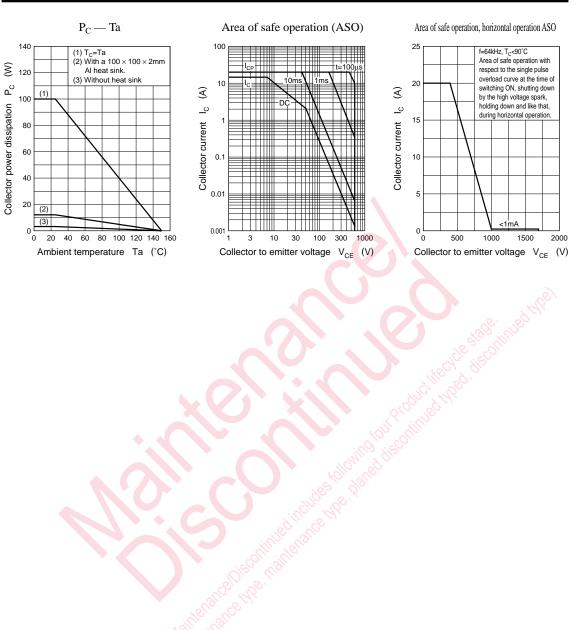
Parameter	Symbol	Ratings	Unit	
Collector to base voltage	V _{CBO}	1700	V	
	V _{CES}	1700	V	
Collector to emitter voltage	V _{CEO}	600	V	
Emitter to base voltage	V _{EBO}	5	V	
Peak collector current	I _{CP}	20	А	
Collector current	I _C	15	А	
Base current	IB	8	А	
Collector power T _C =25°C		100		
dissipation Ta=25°C	P _C	3	W	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Absolute Maximum Ratings $(T_c=25^{\circ}C)$



Electrical Characteristics (T_c=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = 1000V, I_E = 0$			50	μΑ
		$V_{CB} = 1700V, I_E = 0$			1	mA
Emitter cutoff current	I _{EBO}	$V_{EB} = 5V, I_C = 0$			50	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 5V, I_C = 7.5A$	6		14	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_{C} = 7.5A, I_{B} = 1.88A$			3	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_{C} = 7.5A, I_{B} = 1.88A$			1.5	V
Transition frequency	f _T	$V_{CE} = 10V, I_C = 0, f = 0.5MHz$		3		MHz
Storage time	t _{stg}	$I_{C} = 8A, I_{B1} = 2A, I_{B2} = -4A$			4.0	μs
Fall time	t _f				0.3	μs



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